

REMARKS

Claim 1 has been amended to recite that the thermoplastic polymer layer (A) *consists essentially of* said thermoplastic polymer. Support is found, for example, by reference to the working examples in the specification where the outer layer was formed from a thermoplastic elastomer TPU-1, TPU-2 or TPU-3.

Review and reconsideration on the merits are requested.

Claims 1 and 5-15 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent 6,776,195 to Blasko et al in view of U.S. Patent 6,881,460 to Inaba.

Blasko et al was cited as disclosing a tubular polymeric laminate including an inner fluoropolymer layer (thermoplastic resin layer), an outer nylon layer (polyamide-based resin layer), and another resin layer (thermoplastic polymer layer) bonded directly to the fluoropolymer layer. Further, because it is an ethylene-based fluoropolymer, the Examiner considered that the thermoplastic resin would have a carbonyl functional group, where the first layer (polyamide) is directly bonded to the second layer (fluoropolymer) through thermal “fusion” bonding. The Examiner relied on Inaba et al as disclosing a multilayer molding having a polyamide-based resin as an outer layer having an amine value of 10-35 (equivalents/10⁶ g) so as to provide a satisfactory level of adhesion strength to an inner layer comprising a fluorine-containing resin. The reason for rejection was that it would have been obvious to apply the amine value of Inaba et al to the polyamide-based resin of Blasko et al so as to promote adhesion and mechanical properties in a multilayer resin molding.

As set forth in the Remarks portion of the Amendment filed April 15, 2010, the rejection should be withdrawn because Blasko et al does not disclose a three-layered laminate firmly adhered at both the interface between the thermoplastic polymer layer (A) and the polyamide-

based resin layer (B) and between the polyamide-based resin layer (B) and the thermoplastic resin layer (C) as recited in present claim 1.

In the Response to Arguments, the Examiner noted that Blasko et al discloses an invention of two or more layer tubular polymeric laminates having an inner fluoropolymer layer and an outer nylon layer, and that resin layers may be included between the member 10 and the innermost reinforcement layer 130a of Fig. 2. Based thereon, the Examiner concluded that the polymeric laminate of Blasko et al has a three-layered structure with two (2) thermoplastic resin layers bonded to a middle layer of a polyamide-based resin.

Applicants respond as follows.

The laminated resin molding of amended claim 1 comprises a thermoplastic polymer layer (A), a polyamide-based resin layer (B) and a thermoplastic resin layer (C). Further, the thermoplastic polymer *consists essentially of* a thermoplastic polymer. In other words, the thermoplastic polymer is not an electrically conductive layer.

In contrast, Blasko et al discloses that separate electrically conductive resin layers may be included. See col. 9, lines 13 to 20. Blasko et al does not disclose that a nonconductive layer may be included.

Moreover, the layer is in the form of spiral or cigarette-wrapper tapes. Since such layer cannot be formed by extrusion, the layer is not adhered by thermal fusion bonding and not firmly adhered to the member 10.

In addition, although Blasko et al discloses “resin layers,” Blasko et al does not disclose a thermoplastic resin.

The electrically conductive layer may be between the member 10 and the innermost reinforcement layer 130a, between the reinforcement layers 130, or between the outermost reinforcement layer 130b and cover 140.

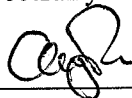
Namely, a skilled artisan would have to select a thermoplastic resin *in addition to* the layer structure of the invention, in order to achieve the laminated resin molding as defined in amended claim 1. For this reason, the amended claims are patentable over the cited prior art, and withdrawal of the foregoing rejection under 35 U.S.C. § 103(a) is respectfully requested.

Withdrawal of all rejections and allowance of claims 1 and 5-15 is earnestly solicited.

In the event that the Examiner believes that it may be helpful to advance the prosecution of this application, the Examiner is invited to contact the undersigned at the local Washington, D.C. telephone number indicated below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Abraham J. Rosner
Registration No. 33,276

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: October 7, 2010